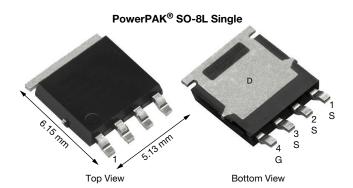


www.vishay.com

Vishay Siliconix

Automotive N-Channel 40 V (D-S) 175 °C MOSFET



PRODUCT SUMMARY	
V _{DS} (V)	40
$R_{DS(on)}(\Omega)$ at $V_{GS} = 10 \text{ V}$	0.0050
$R_{DS(on)}(\Omega)$ at $V_{GS} = 4.5 \text{ V}$	0.0075
I _D (A)	60
Configuration	Single

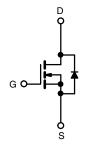
FEATURES

- TrenchFET® power MOSFET
- AEC-Q101 qualified ^c
- 100 % R_q and UIS tested
- Material categorization: for definitions of compliance please see www.vishav.com/doc?99912





ROHS
COMPLIANT
HALOGEN
FREE



N-Channel MOSFET

ORDERING INFORMATION	
Package	PowerPAK SO-8L
Lead (Pb)-free and halogen-free	SQJ446EP-T1 (for detailed order number please see www.vishay.com/doc?79771)

ABSOLUTE MAXIMUM RATING	S (T _C = 25 °C, unles	s otherwise noted)		
PARAMETER	SYMBOL	LIMIT	UNIT		
Drain-Source Voltage		V_{DS}	40	V	
Gate-Source Voltage		V_{GS}	± 20	V	
Continuous Drain Current	T _C = 25 °C	I-	60		
Continuous Diain Current	T _C = 125 °C	I _D	35		
Continuous Source Current (Diode Conduction)		Is	42	Α	
Pulsed Drain Current ^a		I _{DM}	200		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	42		
Single Pulse Avalanche Energy	L = 0.1 IIII	E _{AS}	88	mJ	
Maximum Power Dissipation ^a	T _C = 25 °C	D_	46	W	
Maximum Fower Dissipation 4	T _C = 125 °C	P _D	15		
Operating Junction and Storage Temperature	e Range	T _J , T _{stg}	-55 to +175	°C	
Soldering Recommendations (Peak Tempera	iture) ^{d, e}		260	C	

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount b	R_{thJA}	65	°C/W
Junction-to-Case (Drain)		R_{thJC}	3.2	C/VV

Notes

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%$
- b. When mounted on 1" square PCB (FR4 material)
- c. Parametric verification ongoing
- d. See solder profile www.vishay.com/doc?73257). The PowerPAK SO-8L is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components



Vishay Siliconix

PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static						l	
Drain-Source Breakdown Voltage	V _{DS}	V _{GS}	= 0, I _D = 250 μA	40	-	-	V
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$		1.5	2.0	2.5	V
Gate-Source Leakage	I _{GSS}	V _{DS} =	$0 \text{ V}, \text{ V}_{GS} = \pm 20 \text{ V}$	-	-	± 100	nA
		V _{GS} = 0 V	V _{DS} = 40 V	-	-	1	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V$	V _{DS} = 40 V, T _J = 125 °C	-	-	50	μΑ
-		V _{GS} = 0 V	V _{DS} = 40 V, T _J = 175 °C	-	-	150	
On-State Drain Current ^a	I _{D(on)}	V _{GS} = 10 V	$V_{DS} \ge 5 V$	30	-	-	Α
		V _{GS} = 10 V	I _D = 14 A	-	0.0037	0.0050	
Drain-Source On-State Resistance a		V _{GS} = 4.5 V	I _D = 12 A	-	0.0044	0.0075	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 14 A, T _J = 125 °C	-	0.0059	-	Ω
		V _{GS} = 10 V	I _D = 14 A, T _J = 175 °C	-	0.0068	-	1
Forward Transconductance b	9 _{fs}	V _{DS}	= 15 V, I _D = 14 A	-	125	-	S
Dynamic ^b							
Input Capacitance	C _{iss}			-	3170	4220	
Output Capacitance	C _{oss}	$V_{GS} = 0 V$	$V_{DS} = 20 \text{ V}, f = 1 \text{ MHz}$	-	430	575	pF
Reverse Transfer Capacitance	C _{rss}			-	175	232	
Total Gate Charge c	Qg			-	48	65	
Gate-Source Charge c	Q _{gs}	V _{GS} = 10 V	$V_{DS} = 20 \text{ V}, I_{D} = 20 \text{ A}$	-	7.4	-	nC
Gate-Drain Charge ^c	Q _{gd}			-	11	-	
Gate Resistance	R_g		f = 1 MHz	0.3	0.6	1.2	Ω
Turn-On Delay Time ^c	t _{d(on)}			-	8	12	
Rise Time ^c	t _r	$V_{DD} = 20 \text{ V}, R_{L} = 2 \Omega$		-	18	27	_
Turn-Off Delay Time ^c	t _{d(off)}	$I_D \cong 10 A$,	V_{GEN} = 10 V, R_g = 1 Ω	-	24	35	ns
Fall Time ^c	t _f	1		-	14	21	
Source-Drain Diode Ratings and Chara	cteristics b				•		
Pulsed Current ^a	I _{SM}			-	-	286	Α
Forward Voltage	V_{SD}	lc =	10.6 A, V _{GS} = 0	_	0.8	1.2	V

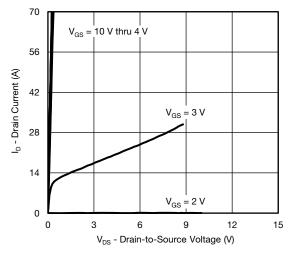
Notes

- a. Pulse test; pulse width $\leq 300~\mu s,\,duty~cycle \leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

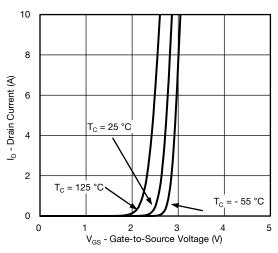
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



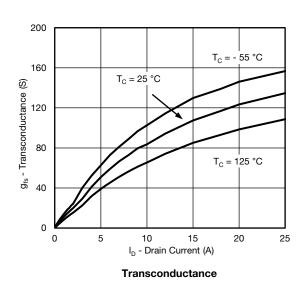
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)

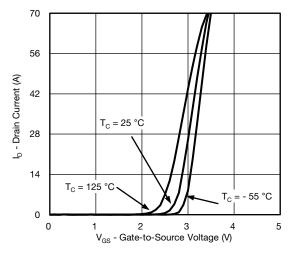


Output Characteristics

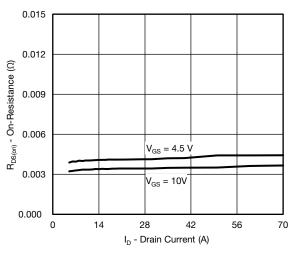


Transfer Characteristics

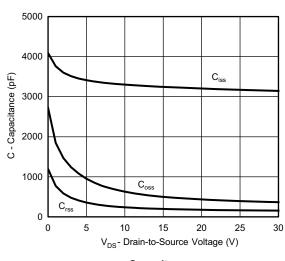




Transfer Characteristics

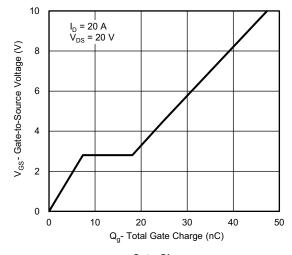


On-Resistance vs. Drain Current

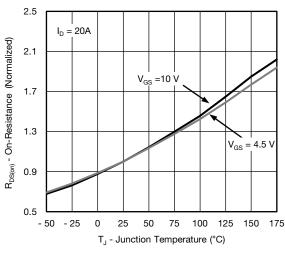




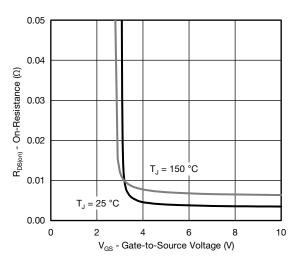
TYPICAL CHARACTERISTICS (T_A = 25 °C, unless otherwise noted)



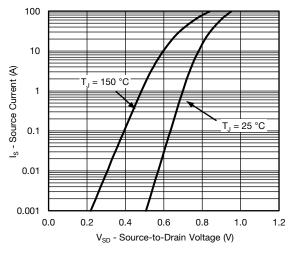
Gate Charge



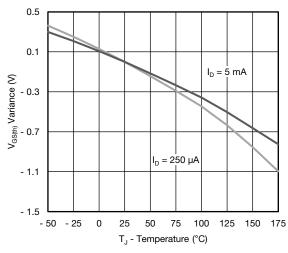
On-Resistance vs. Junction Temperature



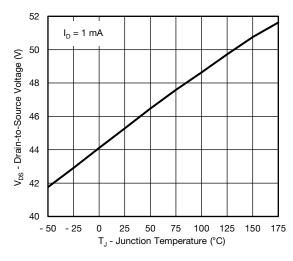
On-Resistance vs. Gate-to-Source Voltage



Source Drain Diode Forward Voltage



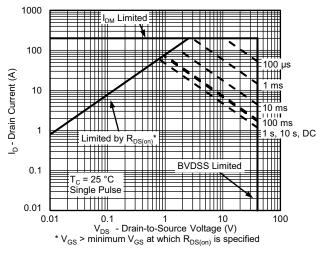
Threshold Voltage



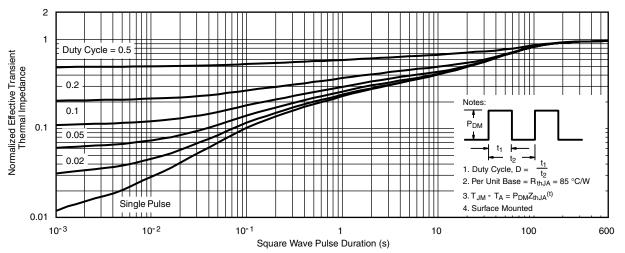
Drain Source Breakdown vs. Junction Temperature



THERMAL RATINGS ($T_A = 25$ °C, unless otherwise noted)



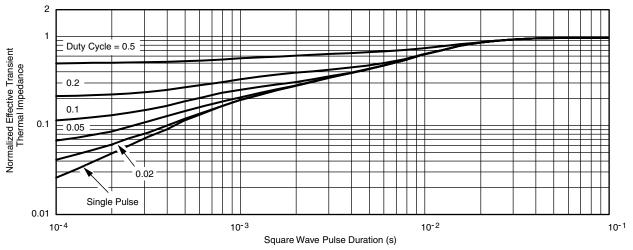
Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



THERMAL RATINGS (T_A = 25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Case

Note

- The characteristics shown in the two graphs
 - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
 - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?62873.



PowerPAK® SO-8L Case Outline 2





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DIM	MILLIMETERS			INCHES			
DIM.	MIN.	NOM.	MAX.	MIN.	NOM.	MAX	
Α	1.00	1.07	1.14	0.039	0.042	0.045	
A1	0.00	-	0.127	0.00	-	0.005	
b	0.33	0.41	0.48	0.013	0.016	0.019	
b1	0.44	0.51	0.58	0.017	0.020	0.023	
b2	4.80	4.90	5.00	0.189	0.193	0.197	
b3		0.094			0.004		
b4		0.47			0.019		
С	0.20	0.25	0.30	0.008	0.010	0.012	
D	5.00	5.13	5.25	0.197	0.202	0.207	
D1	4.80	4.90	5.00	0.189	0.193	0.197	
D2	3.86	3.96	4.06	0.152	0.156	0.160	
D3	1.63	1.73	1.83	0.064	0.068	0.072	
е		1.27 BSC		0.050 BSC			
Е	6.05	6.15	6.25	0.238	0.242	0.246	
E1	4.27	4.37	4.47	0.168	0.172	0.176	
E2	2.75	2.85	2.95	0.108	0.112	0.116	
E3	6.05	6.22	6.40	0.238	0.245	0.252	
F	-	-	0.15	-	-	0.006	
L	0.62	0.72	0.82	0.024	0.028	0.032	
L1	0.92	1.07	1.22	0.036	0.042	0.048	
K		0.51			0.020		
W	0.23			0.009			
W1		0.41		0.016			
W2	2.82		0.111				
W3		2.96			0.117		
θ	0°	-	10°	0°	-	10°	

DWG: 6044

Note

• Millimeters will govern



RECOMMENDED MINIMUM PAD FOR PowerPAK® SO-8L SINGLE



Recommended Minimum Pads Dimensions in mm (inches)



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